Ir. Yau Chau Fong

Organizing Chairman, Professor Chin Fung Kee Memorial Lecture

c/o Ms. Janet Lim

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## 31st ANNUAL PROFESSOR CHIN FUNG KEE MEMORIAL LECTURE

### My Industry to Academia Research Journey and Energizing Innovations among Malaysian Engineers

31<sup>st</sup> July 2021

No.	Name	IEM M'ship No.	Fees
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Enclosed herewith is a cheque no.: for the sum of RM issued in favour of "PROF CHIN FUNG KEE LECTURE FUND". I/We understand that the fee is not refundable if I/we withdraw after my/our registration is accepted by the Committee but substitution of participants will be allowed. If I/we fail to attend the Lecture, the fee paid would not be refunded.			
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## 31<sup>ST</sup> Annual Professor Chin Fung Kee Memorial Lecture

To be delivered by

#### Prof Dr. Chuah Mooi Choo

Full Professor, Associate Chair of CSE Dept, Lehigh University IEEE Fellow, NAI Fellow

on the subject of

# My Industry to Academia Research Journey and Energizing Innovations among Malaysian Engineers

Saturday, 31st July 2021 at 9.00 a.m.

(via Webinar)

Ir. Yau Chau Fong Organizing Chairman

Prof Emeritus Tan Sri Dato' Ir. Dr. Chuah Hean Teik, Ir. Dr. Ting Wen Hui & Ir. Dr. Chan Sin Fatt Advisors

Jointly organized by:

The Institution of Engineers, Malaysia and Universiti Malaya Engineering Alumni Association (2017)

BEM Approved CPD/PDP Hours: 1 Ref. No: IEM21/HQ/177/L (w)

#### SYNOPSIS OF LECTURE

In this talk, the speaker will first share her research journey from industry to academia, initially in Malaysia and then in United States. She was fortunate to receive a strong science & mathematical education in Malaysia, trained as an engineer at University of Malaya, worked with a team of talented R&D engineers at Motorola Communication Sectors Sdn. Bhd. in Penang before she went to United States for her graduate studies. In United States, again she was fortunate to have several mentors that help to inspire her to conduct great research first in industry and then in academia. Next, based on her experience, she will share some main ingredients one needs to cultivate to conduct great research, e.g., curiosity, diligence, and perseverance. Subsequently, she will also share her thoughts on how industry partners, academic leaders, and Malaysian government can collaborate to energize innovations among Malaysian engineers as well as young generations aspiring to be our next generation engineers. Cultivating curiosity in STEM fields at young age, providing opportunities for high school students to appreciate science through solving real life problems with college students, and creating opportunities for faculty members in STEM fields to spend sabbatical semesters at top universities or industry R&D laboratories to horn their skills are necessary steps to energize innovations among Malaysian engineers.

#### C.V. of the Speaker

**Dr. Chuah** graduated with BEng (Honors) from University of Malaya in 1984 and MSc and Ph.D. in Electrical Engineering from University of California San Diego in 1989 and 1991 respectively. She spent 12 years at AT&T Bell Laboratories and Lucent Bell Laboratories where she was a Member of Technical Staff, a Distinguished Member of Technical Staff and later a Technical Manager. She joined Lehigh University as an associate professor in Jan 2004. She is currently a Full Professor and the associate chair of the Computer Science & Engineering department at Lehigh University.

Her research interests include mobile health, computer vision, healthcare data mining, cloud security and security design for Cyber Physical Systems. She has authored/coauthored more than 150 papers in international journals and conferences. Her research has been funded by major funding agencies in United States, e.g., National Science Foundation, DARPA, DOE and companies such as Qualcomm and FORD. She has served as Technical Co-Chairs for several top international conferences such as Technical Co-Chair for IEEE INFOCOM 2010, Symposium Co-Chair for Next Generation Networking Symposium for IEEE Globecom 2013, Technical Co-Chair for ACM/IEEE CHASE Conference and IEEE MASS 2019 Security & Privacy Track Co-Chair. She has also served as associate editors for several top IEEE transactions such as IEEE Transactions on Mobile Computing and IEEE Transactions on Parallel & Distributed Computing Systems. She has been awarded 63 US patents and 15 international patents based on her research work at Bell Laboratories in the area of wireless data system design, resource and mobility management design, MAC layer quality of service design etc. Based on her strong contributions in these areas, she was elevated to be an IEEE Fellow in 2015 and a NAI Fellow in 2017.

#### **Registration Fee (Webinar)**

Members, IEM - RM10.00
Members, Engineering Graduates Alumni Association, Universiti Malaya - RM10.00

Non-members - RM25.00

<u>IMPORTANT:</u> All registration fees must be FULLY paid before commencement of the Lecture.

#### **Registration Methods**

Option 1 – Register via IEM Portal (online payment available) at <a href="mailto:shorturl.at/dszN6">shorturl.at/dszN6</a>

Option 2 – Email your filled registration form to IEM Secretariat at <a href="mailto:janet@iem.org.my">janet@iem.org.my</a>

Option 3 – Fax your filled registration form to IEM Secretariat at Fax No.: 03-7957 7678

All cheques/bank drafts must be crossed and made payable to "PROF CHIN FUNG KEE LECTURE FUND".

#### **Programme**

Date : Saturday, 31st July 2021

Time : 9.00 a.m. - 9.45 a.m. - Lecture

9.45 a.m. - 10.00 a.m. - Q&A Session

#### REGISTRATION IS COMPULSORY

Limited to 500 participants only (first come, first served basis)

The Zoom Webinar link will be emailed to the successful registrants 24 hours before the event.

Registration Deadline: 15th July 2021